

Bill of Materials

TI DESIGNS

TIPD107: Low-Level V-to-I Converter Reference Design

| Qty | Value | Designator | Description | Manufacturer | Manufacturer Part No. | DigiKeyPartNumber |
|-----|--------|--------------------------------|--|-------------------|-----------------------|-------------------|
| 1 | 4.7uF | C1 | CAP, CERM, 4.7uF, 16V, +/-20%, X7R, 1206 | TDK | C3216X5R1H475K160AB | 445-5994-1-ND |
| 1 | 1000pF | C2 | CAP, CERM, 1000pF, 50V, +/-1%, COG/NPO, 0805 | AVX | 08055A102FAT2A | 478-3759-1-ND |
| 3 | 0.1uF | C3, C4, C5 | CAP, CERM, 0.1uF, 50V, +/-5%, X7R, 0805 | AVX | 08055C104JAT2A | 478-3352-1-ND |
| 4 | | | MACHINE SCREW PAN PHILLIPS 4-40 | B&F Fastener | PMS 440 0038 PH | H782-ND |
| 4 | | H1, H2, H3, H4 | STANDOFF HEX 4-40THR ALUM .500"L | Keystone | 2203 | 2203K-ND |
| 8 | | J1, J2, J3, J4, J5, J6, J7, J8 | Standard Banana Jack, Uninsulated, 5.5mm | Keystone | 575-4 | 574K-ND |
| 1 | 40.2k | R1 | RES, 40.2k ohm, 0.1%, 0.125W, 0805 | TE Connectivity | 676335-2 | A102342CT-ND |
| 1 | 200k | R2 | RES, 200k ohm, 0.1%, 0.125W, 0805 | TE Connectivity | 4-1676971-2 | A102090CT-ND |
| 2 | 100k | R3, R4 | RES, 100k ohm, 1%, 0.125W, 0805 | Vishay-Dale | CRCW0805100KFKEA | 541-100KCCT-ND |
| 1 | 100k | Rset | RES, 100K OHM 0.1% 1/10W 0805 | TE Connectivity | 1676142-2 | A102080CT-ND |
| 2 | | TP1, TP7 | Test Point, TH, Compact, Black | Keystone | 5006 | 5006K-ND |
| 1 | | TP2 | Test Point, TH, Compact, Red | Keystone | 5005 | 5005K-ND |
| 4 | | TP3, TP4, TP5, TP6 | Test Point, TH, Compact, Purple | Keystone | 5124 | 5124K-ND |
| 1 | | U1 | Single JFET Input Op Amp | Texas Instruments | OPA333AID | 296-19545-5-ND |
| 1 | | U2 | IC OPAMP INSTR R-R 1KHZ 8VSSOP | Texas Instruments | INA326EA/2K5 | INA326EA/2K5CT-ND |

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